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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Obsolete
Core Processor	M32C/80
Core Size	16/32-Bit
Speed	32MHz
Connectivity	CANbus, I ² C, IEBus, SIO, UART/USART
Peripherals	DMA, WDT
Number of I/O	85
Program Memory Size	320KB (320K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	24K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	A/D 26x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-BQFP
Supplier Device Package	100-QFP (14x20)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/m30853fwfp-u3

1. Overview

The M32C/85 group (M32C/85, M32C/85T) microcomputer is a single-chip control unit that utilizes high-performance silicon gate CMOS technology with the M32C/80 series CPU core. The M32C/85 group (M32C/85, M32C/85T) is available in 144-pin and 100-pin plastic molded LQFP/QFP packages.

With a 16-Mbyte address space, this microcomputer combines advanced instruction manipulation capabilities to process complex instructions by less bytes and execute instructions at higher speed.

It includes a multiplier and DMAC adequate for office automation, communication devices and industrial equipments, and other high-speed processing applications.

1.1 Applications

Automobiles, audio, cameras, office equipment, communications equipment, portable equipment, etc.

1.4 Product Information

Table 1.3 lists the product information. Figure 1.2 shows the product numbering system.

Table 1.3 M32C/85 Group (1) (M32C/85)

As of July, 2005

Type Number	Package Type	ROM Capacity	RAM Capacity	Remarks
M30855FJGP	PLQP0144KA-A (144P6Q-A)	512K+4K	24K	Flash Memory
M30853FJGP	PLQP0100KB-A (100P6Q-A)			
M30853FJFP	PRQP0100JB-A (100P6S-A)			
M30855FHGP	PLQP0144KA-A (144P6Q-A)	384K+4K		
M30853FHGP	PLQP0100KB-A (100P6Q-A)			
M30853FHFP	PRQP0100JB-A (100P6S-A)			
M30855FWGP	PLQP0144KA-A (144P6Q-A)	320K+4K		
M30853FWGP	PLQP0100KB-A (100P6Q-A)			
M30853FWFP	PRQP0100JB-A (100P6S-A)			
M30855MW-XXXGP	PLQP0144KA-A (144P6Q-A)	320K		Mask ROM
M30853MW-XXXGP	PLQP0100KB-A (100P6Q-A)			
M30853MW-XXXFP	PRQP0100JB-A (100P6S-A)			

Table 1.3 M32C/85 Group (2) (T Version, M32C/85T)

As of July, 2005

Type Number	Package Type	ROM Capacity	RAM Capacity	Remarks
M30855FJTGP	PLQP0144KA-A (144P6Q-A)	512K+4K	24K	Flash Memory T Version (High-reliability 85°C Version)
M30853FJTGP	PLQP0100KB-A (100P6Q-A)			
M30855FHTGP	PLQP0144KA-A (144P6Q-A)	384K+4K		
M30853FHTGP	PLQP0100KB-A (100P6Q-A)			
M30855FWTGP	PLQP0144KA-A (144P6Q-A)	320K+4K		
M30853FWTGP	PLQP0100KB-A (100P6Q-A)			

1.6 Pin Description

Table 1.6 Pin Description (100-Pin and 144-Pin Packages)

Classification	Symbol	I/O Type	Supply Voltage	Function
Power Supply	VCC1, VCC2 VSS	I	–	Apply 3.0 to 5.5V to both VCC1 and VCC2 pins. Apply 0V to the VSS pin. $V_{CC1} \geq V_{CC2}^{(1, 2)}$
Analog Power Supply	AVCC AVSS	I	VCC1	Supplies power to the A/D converter. Connect the AVCC pin to VCC1 and the AVSS pin to VSS
Reset Input	RESET	I	VCC1	The microcomputer is in a reset state when "L" is applied to the RESET pin
CNVss	CNVss	I	VCC1	Switches processor mode. Connect the CNVss pin to VSS to start up in single-chip mode or to VCC1 to start up in microprocessor mode
Input to Switch External Data Bus Width ⁽³⁾	BYTE	I	VCC1	Switches data bus width in external memory space 3. The data bus is 16 bits wide when the BYTE pin is held "L" and 8 bits wide when it is held "H". Set to either. Connect the BYTE pin to VSS to use the microcomputer in single-chip mode
Bus Control Pins ⁽³⁾	D0 to D7	I/O	VCC2	Inputs and outputs data (D0 to D7) while accessing an external memory space with separate bus
	D8 to D15	I/O	VCC2	Inputs and outputs data (D8 to D15) while accessing an external memory space with 16-bit separate bus
	A0 to A22	O	VCC2	Outputs address bits A0 to A22
	A23	O	VCC2	Outputs inversed address bit A23
	A0/D0 to A7/D7	I/O	VCC2	Inputs and outputs data (D0 to D7) and outputs 8 low-order address bits (A0 to A7) by time-sharing while accessing an external memory space with multiplexed bus
	A8/D8 to A15/D15	I/O	VCC2	Inputs and outputs data (D8 to D15) and outputs 8 middle-order address bits (A8 to A15) by time-sharing while accessing an external memory space with 16-bit multiplexed bus
	CS0 to CS3	O	VCC2	Outputs CS0 to CS3 that are chip-select signals specifying an external space
	WRL / WR WRH / BHE RD	O	VCC2	Outputs WRL, WRH, (WR, BHE) and RD signals. WRL and WRH can be switched with WR and BHE by program ■ WRL, WRH and RD selected: If external data bus is 16 bits wide, data is written to an even address in external memory space when WRL is held "L". Data is written to an odd address when WRH is held "L". Data is read when RD is held "L". ■ WR, BHE and RD selected: Data is written to external memory space when WR is held "L". Data in an external memory space is read when RD is held "L". An odd address is accessed when BHE is held "L". Select WR, BHE and RD for external 8-bit data bus.
	ALE	O	VCC2	ALE is a signal latching the address
	HOLD	I	VCC2	The microcomputer is placed in a hold state while the HOLD pin is held "L"
	HLDA	O	VCC2	Outputs an "L" signal while the microcomputer is placed in a hold state
	RDY	I	VCC2	Bus is placed in a wait state while the RDY pin is held "L"

I : Input O : Output I/O : Input and output

NOTES:

1. VCC1 is hereinafter referred to as VCC unless otherwise noted.
2. Apply 4.2 to 5.5V to the VCC1 and VCC2 pins when using M32C/85T. $V_{CC1}=V_{CC2}$.
3. Bus control pins in M32C/85T cannot be used.

2.1.8.5 Register Bank Select Flag (B)

The register bank 0 is selected when the B flag is set to "0". The register bank 1 is selected when this flag is set to "1".

2.1.8.6 Overflow Flag (O)

The O flag is set to "1" when the result of an arithmetic operation overflows; otherwise "0".

2.1.8.7 Interrupt Enable Flag (I)

The I flag enables a maskable interrupt.

Interrupt is disabled when the I flag is set to "0" and enabled when the I flag is set to "1". The I flag is set to "0" when an interrupt is acknowledged.

2.1.8.8 Stack Pointer Select Flag (U)

ISP is selected when the U flag is set to "0". USP is selected when this flag is set to "1".

The U flag is set to "0" when a hardware interrupt is acknowledged or the INT instruction of software interrupt numbers 0 to 31 is executed.

2.1.8.9 Processor Interrupt Priority Level (IPL)

IPL, 3 bits wide, assigns processor interrupt priority levels from level 0 to level 7.

If a requested interrupt has greater priority than IPL, the interrupt is enabled.

2.1.8.10 Reserved Space

When writing to a reserved space, set to "0". When reading, its content is indeterminate.

2.2 High-Speed Interrupt Registers

Registers associated with the high-speed interrupt are as follows:

- Flag save register (SVF)
- PC save register (SVP)
- Vector register (VCT)

2.3 DMAC-Associated Registers

Registers associated with DMAC are as follows:

- DMA mode register (DMD0, DMD1)
- DMA transfer count register (DCT0, DCT1)
- DMA transfer count reload register (DRC0, DRC1)
- DMA memory address register (DMA0, DMA1)
- DMA SFR address register (DSA0, DSA1)
- DMA memory address reload register (DRA0, DRA1)

Address	Register	Symbol	Value after RESET
0150 ₁₆			
0151 ₁₆			
0152 ₁₆			
0153 ₁₆			
0154 ₁₆			
0155 ₁₆			
0156 ₁₆			
0157 ₁₆			
0158 ₁₆			
0159 ₁₆			
015A ₁₆			
015B ₁₆			
015C ₁₆			
015D ₁₆			
015E ₁₆			
015F ₁₆			
0160 ₁₆			
0161 ₁₆			
0162 ₁₆			
0163 ₁₆			
0164 ₁₆			
0165 ₁₆			
0166 ₁₆			
0167 ₁₆			
0168 ₁₆			
0169 ₁₆			
016A ₁₆			
016B ₁₆			
016C ₁₆			
016D ₁₆			
016E ₁₆			
016F ₁₆			
0170 ₁₆			
0171 ₁₆			
0172 ₁₆			
0173 ₁₆			
0174 ₁₆			
0175 ₁₆			
0176 ₁₆			
0177 ₁₆			
0178 ₁₆	Input Function Select Register	IPS	00 ₁₆
0179 ₁₆	Input Function Select Register A	IPSA	00 ₁₆
017A ₁₆			
017B ₁₆			
017C ₁₆			
017D ₁₆ to 01DF ₁₆			

X: Indeterminate

Blank spaces are reserved. No access is allowed.

Address	Register	Symbol	Value after RESET
0210 ₁₆	CAN0 Slot Interrupt Mask Register	C0SIMKR	00 ₁₆ ⁽²⁾
0211 ₁₆			00 ₁₆ ⁽²⁾
0212 ₁₆			
0213 ₁₆			
0214 ₁₆	CAN0 Error Interrupt Mask Register	C0EIMKR	XXXX X000 ₂ ⁽²⁾
0215 ₁₆	CAN0 Error Interrupt Status Register	C0EISTR	XXXX X000 ₂ ⁽²⁾
0216 ₁₆	CAN0 Error Cause Register	C0EFR	00 ₁₆ ⁽²⁾
0217 ₁₆	CAN0 Baud Rate Prescaler	C0BRP	0000 0001 ₂ ⁽²⁾
0218 ₁₆			
0219 ₁₆	CAN0 Mode Register	C0MDR	XXXX XX00 ₂ ⁽²⁾
021A ₁₆			
021B ₁₆			
021C ₁₆			
021D ₁₆			
021E ₁₆			
021F ₁₆			
0220 ₁₆	CAN0 Single Shot Control Register	C0SSCTLR	00 ₁₆ ⁽²⁾
0221 ₁₆			00 ₁₆ ⁽²⁾
0222 ₁₆			
0223 ₁₆			
0224 ₁₆	CAN0 Single Shot Status Register	C0SSSTR	00 ₁₆ ⁽²⁾
0225 ₁₆			00 ₁₆ ⁽²⁾
0226 ₁₆			
0227 ₁₆			
0228 ₁₆	CAN0 Global Mask Register Standard ID0	C0GMR0	XXX0 0000 ₂ ⁽²⁾
0229 ₁₆	CAN0 Global Mask Register Standard ID1	C0GMR1	XX00 0000 ₂ ⁽²⁾
022A ₁₆	CAN0 Global Mask Register Extended ID0	C0GMR2	XXXX 0000 ₂ ⁽²⁾
022B ₁₆	CAN0 Global Mask Register Extended ID1	C0GMR3	00 ₁₆ ⁽²⁾
022C ₁₆	CAN0 Global Mask Register Extended ID2	C0GMR4	XX00 0000 ₂ ⁽²⁾
022D ₁₆			
022E ₁₆			
022F ₁₆			
0230 ₁₆	CAN0 Message Slot 0 Control Register / CAN0 Local Mask Register A Standard ID0	C0MCTL0/ C0LMAR0	0000 0000 ₂ ⁽²⁾ XXX0 0000 ₂ ⁽²⁾
0231 ₁₆	CAN0 Message Slot 1 Control Register / CAN0 Local Mask Register A Standard ID1	C0MCTL1/ C0LMAR1	0000 0000 ₂ ⁽²⁾ XX00 0000 ₂ ⁽²⁾
0232 ₁₆	CAN0 Message Slot 2 Control Register / CAN0 Local Mask Register A Extended ID0	C0MCTL2/ C0LMAR2	0000 0000 ₂ ⁽²⁾ XXXX 0000 ₂ ⁽²⁾
0233 ₁₆	CAN0 Message Slot 3 Control Register / CAN0 local Mask Register A Extended ID1	C0MCTL3/ C0LMAR3	00 ₁₆ ⁽²⁾ 00 ₁₆ ⁽²⁾
0234 ₁₆	CAN0 Message Slot 4 Control Register / CAN0 Local Mask Register A Extended ID2	C0MCTL4/ C0LMAR4	0000 0000 ₂ ⁽²⁾ XX00 0000 ₂ ⁽²⁾
0235 ₁₆	CAN0 Message Slot 5 Control Register	C0MCTL5	00 ₁₆ ⁽²⁾
0236 ₁₆	CAN0 Message Slot 6 Control Register	C0MCTL6	00 ₁₆ ⁽²⁾
0237 ₁₆	CAN0 Message Slot 7 Control Register	C0MCTL7	00 ₁₆ ⁽²⁾
0238 ₁₆	CAN0 Message Slot 8 Control Register / CAN0 Local Mask Register B Standard ID0	C0MCTL8/ C0LMBR0	0000 0000 ₂ ⁽²⁾ XXX0 0000 ₂ ⁽²⁾
0239 ₁₆	CAN0 Message Slot 9 Control Register / CAN0 Local Mask Register B Standard ID1	C0MCTL9/ C0LMBR1	0000 0000 ₂ ⁽²⁾ XX00 0000 ₂ ⁽²⁾

(Note 1)

X: Indeterminate

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NOTES:

1. The BANKSEL bit in the C0CTLR1 register switches functions for addresses 0220₁₆ to 023F₁₆.
2. Values are obtained by setting the SLEEP bit in the C0SLPR register to "1" (sleep mode exited) after reset and applying the clock to the CAN module.

Address	Register	Symbol	Value after RESET	
023A ₁₆	CAN0 Message Slot 10 Control Register / CAN0 Local Mask Register B Extended ID0	C0MCTL10/ C0LMBR2	0000 0000 ₂ ⁽²⁾ XXXX 0000 ₂ ⁽²⁾	(Note 1)
023B ₁₆	CAN0 Message Slot 11 Control Register / CAN0 Local Mask Register B Extended ID1	C0MCTL11/ C0LMBR3	00 ₁₆ ⁽²⁾ 00 ₁₆ ⁽²⁾	
023C ₁₆	CAN0 Message Slot 12 Control Register / CAN0 Local Mask Register B Extended ID2	C0MCTL12/ C0LMBR4	0000 0000 ₂ ⁽²⁾ XX00 0000 ₂ ⁽²⁾	
023D ₁₆	CAN0 Message Slot 13 Control Register	C0MCTL13	00 ₁₆ ⁽²⁾	
023E ₁₆	CAN0 Message Slot 14 Control Register	C0MCTL14	00 ₁₆ ⁽²⁾	
023F ₁₆	CAN0 Message Slot 15 Control Register	C0MCTL15	00 ₁₆ ⁽²⁾	
0240 ₁₆	CAN0 Slot Buffer Select Register	C0SBS	00 ₁₆ ⁽²⁾	
0241 ₁₆	CAN0 Control Register 1	C0CTLR1	X000 00XX ₂ ⁽²⁾	
0242 ₁₆	CAN0 Sleep Control Register	C0SLPR	XXXX XXX0 ₂	
0243 ₁₆				
0244 ₁₆ 0245 ₁₆	CAN0 Acceptance Filter Support Register	C0AFS	00 ₁₆ ⁽²⁾ 01 ₁₆ ⁽²⁾	
0246 ₁₆				
0247 ₁₆				
0248 ₁₆				
0249 ₁₆				
024A ₁₆				
024B ₁₆				
024C ₁₆				
024D ₁₆				
024E ₁₆				
024F ₁₆				
0250 ₁₆	CAN1 Slot Buffer Select Register	C1SBS	00 ₁₆ ⁽³⁾	
0251 ₁₆	CAN1 Control Register 1	C1CTLR1	X000 00XX ₂ ⁽³⁾	
0252 ₁₆	CAN1 Sleep Control Register	C1SLPR	XXXX XXX0 ₂	
0253 ₁₆				
0254 ₁₆ 0255 ₁₆	CAN1 Acceptance Filter Support Register	C1AFS	00 ₁₆ ⁽³⁾ 01 ₁₆ ⁽³⁾	
0256 ₁₆				
0257 ₁₆				
0258 ₁₆				
0259 ₁₆				
025A ₁₆				
025B ₁₆				
025C ₁₆				
025D ₁₆				
025E ₁₆				
025F ₁₆				

X: Indeterminate

Blank spaces are reserved. No access is allowed.

NOTES:

1. The BANKSEL bit in the C0CTLR1 register switches functions for addresses 0220₁₆ to 023F₁₆.
2. Values are obtained by setting the SLEEP bit in the C0SLPR register to "1" (sleep mode exited) after reset and applying the clock to the CAN module.
3. Values are obtained by setting the SLEEP bit in the C1SLPR register to "1" (sleep mode exited) after reset and applying the clock to the CAN module.

Address	Register	Symbol	Value after RESET
02E0 ₁₆	X/Y Control Register	XYC	XXXX XX00 ₂
02E1 ₁₆			
02E2 ₁₆			
02E3 ₁₆			
02E4 ₁₆	UART1 Special Mode Register 4	U1SMR4	00 ₁₆
02E5 ₁₆	UART1 Special Mode Register 3	U1SMR3	00 ₁₆
02E6 ₁₆	UART1 Special Mode Register 2	U1SMR2	00 ₁₆
02E7 ₁₆	UART1 Special Mode Register	U1SMR	00 ₁₆
02E8 ₁₆	UART1 Transmit/Receive Mode Register	U1MR	00 ₁₆
02E9 ₁₆	UART1 Bit Rate Register	U1BRG	XX ₁₆
02EA ₁₆	UART1 Transmit Buffer Register	U1TB	XX ₁₆
02EB ₁₆			XX ₁₆
02EC ₁₆	UART1 Transmit/Receive Control Register 0	U1C0	0000 1000 ₂
02ED ₁₆	UART1 Transmit/Receive Control Register 1	U1C1	0000 0010 ₂
02EE ₁₆	UART1 Receive Buffer Register	U1RB	XX ₁₆
02EF ₁₆			XX ₁₆
02F0 ₁₆			
02F1 ₁₆			
02F2 ₁₆			
02F3 ₁₆			
02F4 ₁₆	UART4 Special Mode Register 4	U4SMR4	00 ₁₆
02F5 ₁₆	UART4 Special Mode Register 3	U4SMR3	00 ₁₆
02F6 ₁₆	UART4 Special Mode Register 2	U4SMR2	00 ₁₆
02F7 ₁₆	UART4 Special Mode Register	U4SMR	00 ₁₆
02F8 ₁₆	UART4 Transmit/Receive Mode Register	U4MR	00 ₁₆
02F9 ₁₆	UART4 Bit Rate Register	U4BRG	XX ₁₆
02FA ₁₆	UART4 Transmit Buffer Register	U4TB	XX ₁₆
02FB ₁₆			XX ₁₆
02FC ₁₆	UART4 Transmit/Receive Control Register 0	U4C0	0000 1000 ₂
02FD ₁₆	UART4 Transmit/Receive Control Register 1	U4C1	0000 0010 ₂
02FE ₁₆	UART4 Receive Buffer Register	U4RB	XX ₁₆
02FF ₁₆			XX ₁₆
0300 ₁₆	Timer B3, B4, B5 Count Start Flag	TBSR	000X XXXX ₂
0301 ₁₆			
0302 ₁₆	Timer A1-1 Register	TA11	XX ₁₆
0303 ₁₆			XX ₁₆
0304 ₁₆	Timer A2-1 Register	TA21	XX ₁₆
0305 ₁₆			XX ₁₆
0306 ₁₆	Timer A4-1 Register	TA41	XX ₁₆
0307 ₁₆			XX ₁₆
0308 ₁₆	Three-Phase PWM Control Register 0	INVC0	00 ₁₆
0309 ₁₆	Three-Phase PWM Control Register 1	INVC1	00 ₁₆
030A ₁₆	Three-Phase Output Buffer Register 0	IDB0	XX11 1111 ₂
030B ₁₆	Three-Phase Output Buffer Register 1	IDB1	XX11 1111 ₂
030C ₁₆	Dead Time Timer	DTT	XX ₁₆
030D ₁₆	Timer B2 Interrupt Generation Frequency Set Counter	ICTB2	XX ₁₆
030E ₁₆			
030F ₁₆			

X: Indeterminate

Blank spaces are reserved. No access is allowed.

<144-pin package>

Address	Register	Symbol	Value after RESET
03A0 ₁₆	Function Select Register A8	PS8	X000 0000 ₂
03A1 ₁₆	Function Select Register A9	PS9	00 ₁₆
03A2 ₁₆			
03A3 ₁₆			
03A4 ₁₆			
03A5 ₁₆			
03A6 ₁₆			
03A7 ₁₆	Function Select Register D1	PSD1	X0XX XX00 ₂
03A8 ₁₆			
03A9 ₁₆			
03AA ₁₆			
03AB ₁₆			
03AC ₁₆	Function Select Register C2	PSC2	XXXX X00X ₂
03AD ₁₆	Function Select Register C3	PSC3	X0XX XXXX ₂
03AE ₁₆			
03AF ₁₆	Function Select Register C	PSC	00X0 0000 ₂
03B0 ₁₆	Function Select Register A0	PS0	00 ₁₆
03B1 ₁₆	Function Select Register A1	PS1	00 ₁₆
03B2 ₁₆	Function Select Register B0	PSL0	00 ₁₆
03B3 ₁₆	Function Select Register B1	PSL1	00 ₁₆
03B4 ₁₆	Function Select Register A2	PS2	00X0 0000 ₂
03B5 ₁₆	Function Select Register A3	PS3	00 ₁₆
03B6 ₁₆	Function Select Register B2	PSL2	00X0 0000 ₂
03B7 ₁₆	Function Select Register B3	PSL3	00 ₁₆
03B8 ₁₆			
03B9 ₁₆	Function Select Register A5	PS5	XXX0 0000 ₂
03BA ₁₆			
03BB ₁₆			
03BC ₁₆			
03BD ₁₆			
03BE ₁₆			
03BF ₁₆			
03C0 ₁₆	Port P6 Register	P6	XX ₁₆
03C1 ₁₆	Port P7 Register	P7	XX ₁₆
03C2 ₁₆	Port P6 Direction Register	PD6	00 ₁₆
03C3 ₁₆	Port P7 Direction Register	PD7	00 ₁₆
03C4 ₁₆	Port P8 Register	P8	XX ₁₆
03C5 ₁₆	Port P9 Register	P9	XX ₁₆
03C6 ₁₆	Port P8 Direction Register	PD8	00X0 0000 ₂
03C7 ₁₆	Port P9 Direction Register	PD9	00 ₁₆
03C8 ₁₆	Port P10 Register	P10	XX ₁₆
03C9 ₁₆	Port P11 Register	P11	XX ₁₆
03CA ₁₆	Port P10 Direction Register	PD10	00 ₁₆
03CB ₁₆	Port P11 Direction Register	PD11	XXX0 0000 ₂
03CC ₁₆	Port P12 Register	P12	XX ₁₆
03CD ₁₆	Port P13 Register	P13	XX ₁₆
03CE ₁₆	Port P12 Direction Register	PD12	00 ₁₆
03CF ₁₆	Port P13 Direction Register	PD13	00 ₁₆

X: Indeterminate

Blank spaces are reserved. No access is allowed.

<100-pin package>

Address	Register	Symbol	Value after RESET
03D0 ₁₆			
03D1 ₁₆			
03D2 ₁₆	Set default value to "FF ₁₆ "		
03D3 ₁₆	Set default value to "FF ₁₆ "		
03D4 ₁₆			
03D5 ₁₆			
03D6 ₁₆			
03D7 ₁₆			
03D8 ₁₆			
03D9 ₁₆			
03DA ₁₆	Pull-Up Control Register 2	PUR2	00 ₁₆
03DB ₁₆	Pull-Up Control Register 3	PUR3	00 ₁₆
03DC ₁₆	Set default value to "00 ₁₆ "		
03DD ₁₆			
03DE ₁₆			
03DF ₁₆			
03E0 ₁₆	Port P0 Register	P0	XX ₁₆
03E1 ₁₆	Port P1 Register	P1	XX ₁₆
03E2 ₁₆	Port P0 Direction Register	PD0	00 ₁₆
03E3 ₁₆	Port P1 Direction Register	PD1	00 ₁₆
03E4 ₁₆	Port P2 Register	P2	XX ₁₆
03E5 ₁₆	Port P3 Register	P3	XX ₁₆
03E6 ₁₆	Port P2 Direction Register	PD2	00 ₁₆
03E7 ₁₆	Port P3 Direction Register	PD3	00 ₁₆
03E8 ₁₆	Port P4 Register	P4	XX ₁₆
03E9 ₁₆	Port P5 Register	P5	XX ₁₆
03EA ₁₆	Port P4 Direction Register	PD4	00 ₁₆
03EB ₁₆	Port P5 Direction Register	PD5	00 ₁₆
03EC ₁₆			
03ED ₁₆			
03EE ₁₆			
03EF ₁₆			
03F0 ₁₆	Pull-up Control Register 0	PUR0	00 ₁₆
03F1 ₁₆	Pull-up Control Register 1	PUR1	XXXX 0000 ₂
03F2 ₁₆			
03F3 ₁₆			
03F4 ₁₆			
03F5 ₁₆			
03F6 ₁₆			
03F7 ₁₆			
03F8 ₁₆			
03F9 ₁₆			
03FA ₁₆			
03FB ₁₆			
03FC ₁₆			
03FD ₁₆			
03FE ₁₆			
03FF ₁₆	Port Control Register	PCR	XXXX XXX0 ₂

X: Indeterminate

Blank spaces are reserved. No access is allowed.

Table 5.2 Recommended Operating Conditions**(V_{CC1}= V_{CC2}=3.0V to 5.5V at Topr=– 20 to 85°C unless otherwise specified)**

Symbol	Parameter	Standard			Unit
		Min.	Typ.	Max.	
V _{CC1} , V _{CC2}	Supply Voltage (V _{CC1} ≥ V _{CC2})	3.0	5.0	5.5	V
AV _{CC}	Analog Supply Voltage		V _{CC1}		V
V _{SS}	Supply Voltage		0		V
AV _{SS}	Analog Supply Voltage		0		V
V _{IH}	Input High ("H") Voltage	P20-P27, P30-P37, P40-P47, P50-P57, P110-P114, P120-P127, P130-P137 ⁽⁴⁾	0.8V _{CC2}	V _{CC2}	V
		P60-P67, P72-P77, P80-P87 ⁽³⁾ , P90-P97, P100-P107, P140-P146, P150-P157 ⁽⁴⁾ , X _{IN} , RESET, CNV _{SS} , BYTE	0.8V _{CC1}	V _{CC1}	
		P70, P71	0.8V _{CC1}	6.0	
		P00-P07, P10-P17 (in single-chip mode)	0.8V _{CC2}	V _{CC2}	
		P00-P07, P10-P17 (in memory expansion mode and microprocessor mode)	0.5V _{CC2}	V _{CC2}	
V _{IL}	Input Low ("L") Voltage	P20-P27, P30-P37, P40-P47, P50-P57, P110-P114, P120-P127, P130-P137 ⁽⁴⁾	0	0.2V _{CC2}	V
		P60-P67, P70-P77, P80-P87 ⁽³⁾ , P90-P97, P100-P107, P140-P146, P150-P157 ⁽⁴⁾ , X _{IN} , RESET, CNV _{SS} , BYTE	0	0.2V _{CC1}	
		P00-P07, P10-P17 (in single-chip mode)	0	0.2V _{CC2}	
		P00-P07, P10-P17 (in memory expansion mode and microprocessor mode)	0	0.16V _{CC2}	
I _{OH(peak)}	Peak Output High ("H") Current ⁽²⁾	P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P72-P77, P80-P84, P86, P87, P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽⁴⁾		-10.0	mA
I _{OH(avg)}	Average Output High ("H") Current ⁽¹⁾	P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P72-P77, P80-P84, P86, P87, P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽⁴⁾		-5.0	mA
I _{OL(peak)}	Peak Output Low ("L") Current ⁽²⁾	P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P70-P77, P80-P84, P86, P87, P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽⁴⁾		10.0	mA
I _{OL(avg)}	Average Output Low ("L") Current ⁽¹⁾	P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P70-P77, P80-P84, P86, P87, P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽⁴⁾		5.0	mA

NOTES:

1. Typical values when average output current is 100ms.
2. Total I_{OL(peak)} for P0, P1, P2, P86, P87, P9, P10, P11, P14 and P15 must be 80mA or less.
 Total I_{OL(peak)} for P3, P4, P5, P6, P7, P80 to P84, P12 and P13 must be 80mA or less.
 Total I_{OH(peak)} for P0, P1, P2, and P11 must be -40mA or less.
 Total I_{OH(peak)} for P86, P87, P9, P10, P14 and P15 must be -40mA or less.
 Total I_{OH(peak)} for P3, P4, P5, P12 and P13 must be -40mA or less.
 Total I_{OH(peak)} for P6, P7, and P80 to P84 must be -40mA or less.
3. V_{IH} and V_{IL} reference for P87 applies when P87 is used as a programmable input port.
 It does not apply when P87 is used as X_{CIN}.
4. P11 to P15 are provided in the 144-pin package only.

$$V_{CC1}=V_{CC2}=5V$$

**Table 5.6 Flash Memory Version Electrical Characteristics (V_{CC1}=4.5 to 5.5V, 3.0 to 3.6V at
T_{opr}=0 to 60°C unless otherwise specified)**

Symbol	Parameter		Standard			Unit
			Min.	Typ.	Max.	
-	Program and Erase Endurance ⁽²⁾		100			cycles
-	Word Program Time (V _{CC1} =5.0V, T _{opr} =25° C)			25	200	μs
-	Lock Bit Program Time			25	200	μs
-	Block Erase Time (V _{CC1} =5.0V, T _{opr} =25° C)	4-Kbyte Block		0.3	4	s
		8-Kbyte Block		0.3	4	s
		32-Kbyte Block		0.5	4	s
		64-Kbyte Block		0.8	4	s
-	All-Unlocked-Block Erase Time ⁽¹⁾				4 x <i>n</i>	s
t _{PS}	Wait Time to Stabilize Flash Memory Circuit				15	μs
-	Data Hold Time (T _{opr} =-40 to 85 ° C)		10			years

NOTES:

1. *n* denotes the number of block to be erased.

2. Number of program-erase cycles per block.

If Program and Erase Endurance is *n* cycle (*n*≠100), each block can be erased and programmed *n* cycles.

For example, if a 4-Kbyte block A is erased after programming a word data 2,048 times, each to a different address, this counts as one program and erase endurance. Data can not be programmed to the same address more than once without erasing the block. (rewrite prohibited).

$$V_{CC1}=V_{CC2}=5V$$

Timing Requirements

($V_{CC1}=V_{CC2}=4.2$ to $5.5V$, $V_{SS}=0V$ at $T_{opr}=-20$ to $85^{\circ}C$ unless otherwise specified)

Table 5.9 External Clock Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
t_c	External Clock Input Cycle Time	31.25		ns
$t_{W(H)}$	External Clock Input High ("H") Width	13.75		ns
$t_{W(L)}$	External Clock Input Low ("L") Width	13.75		ns
t_r	External Clock Rise Time		5	ns
t_f	External Clock Fall Time		5	ns

Table 5.10 Memory Expansion Mode and Microprocessor Mode

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{ac1(RD-DB)}$	Data Input Access Time (RD standard)		(Note 1)	ns
$t_{ac1(AD-DB)}$	Data Input Access Time (AD standard, CS standard)		(Note 1)	ns
$t_{ac2(RD-DB)}$	Data Input Access Time (RD standard, when accessing a space with the multiplexed bus)		(Note 1)	ns
$t_{ac2(AD-DB)}$	Data Input Access Time (AD standard, when accessing a space with the multiplexed bus)		(Note 1)	ns
$t_{su(DB-BCLK)}$	Data Input Setup Time	26		ns
$t_{su(RDY-BCLK)}$	$\overline{RDY}$ Input Setup Time	26		ns
$t_{su(HOLD-BCLK)}$	$\overline{HOLD}$ Input Setup Time	30		ns
$t_{h(RD-DB)}$	Data Input Hold Time	0		ns
$t_{h(BCLK-RDY)}$	$\overline{RDY}$ Input Hold Time	0		ns
$t_{h(BCLK-HOLD)}$	$\overline{HOLD}$ Input Hold Time	0		ns
$t_{d(BCLK-HLDA)}$	$\overline{HLDA}$ Output Delay Time		25	ns

NOTES:

1. Values can be obtained from the following equations, according to BCLK frequency and external bus cycles. Insert a wait state or lower the operation frequency, $f_{(BCLK)}$, if the calculated value is negative.

$$t_{ac1(RD-DB)} = \frac{10^9 \times m}{f_{(BCLK)} \times 2} - 35 \quad [\text{ns}] \text{ (if external bus cycle is } a\phi + b\phi, m=(bx2)+1)$$

$$t_{ac1(AD-DB)} = \frac{10^9 \times n}{f_{(BCLK)}} - 35 \quad [\text{ns}] \text{ (if external bus cycle is } a\phi + b\phi, n=a+b)$$

$$t_{ac2(RD-DB)} = \frac{10^9 \times m}{f_{(BCLK)} \times 2} - 35 \quad [\text{ns}] \text{ (if external bus cycle is } a\phi + b\phi, m=(bx2)-1)$$

$$t_{ac2(AD-DB)} = \frac{10^9 \times p}{f_{(BCLK)} \times 2} - 35 \quad [\text{ns}] \text{ (if external bus cycle is } a\phi + b\phi, p=\{(a+b-1) \times 2\}+1)$$

$$V_{CC1}=V_{CC2}=5V$$

Switching Characteristics

($V_{CC} = 4.2$ to $5.5V$, $V_{SS} = 0V$ at $T_{opr} = -20$ to $85^{\circ}C$ unless otherwise specified)

Table 5.23 Memory Expansion Mode and Microprocessor Mode
(when accessing an external memory space with the multiplexed bus)

Symbol	Parameter	Measurement Condition	Standard		Unit
			Min.	Max.	
$t_{d(BCLK-AD)}$	Address Output Delay Time	See Figure 5.2		18	ns
$t_{h(BCLK-AD)}$	Address Output Hold Time (BCLK standard)		-3		ns
$t_{h(RD-AD)}$	Address Output Hold Time (RD standard) ⁽⁵⁾		(Note 1)		ns
$t_{h(WR-AD)}$	Address Output Hold Time (WR standard) ⁽⁵⁾		(Note 1)		ns
$t_{d(BCLK-CS)}$	Chip-Select Signal Output Delay Time			18	ns
$t_{h(BCLK-CS)}$	Chip-Select Signal Output Hold Time (BCLK standard)		-3		ns
$t_{h(RD-CS)}$	Chip-Select Signal Output Hold Time (RD standard) ⁽⁵⁾		(Note 1)		ns
$t_{h(WR-CS)}$	Chip-Select Signal Output Hold Time (WR standard) ⁽⁵⁾		(Note 1)		ns
$t_{d(BCLK-RD)}$	RD Signal Output Delay Time			18	ns
$t_{h(BCLK-RD)}$	RD Signal Output Hold Time		-5		ns
$t_{d(BCLK-WR)}$	WR Signal Output Delay Time			18	ns
$t_{h(BCLK-WR)}$	WR Signal Output Hold Time		-5		ns
$t_{d(DB-WR)}$	Data Output Delay Time (WR standard)		(Note 2)		ns
$t_{h(WR-DB)}$	Data Output Hold Time (WR standard) ⁽⁵⁾		(Note 1)		ns
$t_{d(BCLK-ALE)}$	ALE Signal Output Delay Time (BCLK standard)			18	ns
$t_{h(BCLK-ALE)}$	ALE Signal Output Hold Time (BCLK standard)		-2		ns
$t_{d(AD-ALE)}$	ALE Signal Output Delay Time (address standard)		(Note 3)		ns
$t_{h(ALE-AD)}$	ALE Signal Output Hold Time (address standard)		(Note 4)		ns
$t_{dZ(RD-AD)}$	Address Output Float Start Time			8	ns

NOTES:

1. Values can be obtained from the following equations, according to BCLK frequency.

$$t_{h(RD-AD)} = \frac{10^9}{f_{(BCLK)} \times 2} - 10 \quad [ns]$$

$$t_{h(WR-AD)} = \frac{10^9}{f_{(BCLK)} \times 2} - 10 \quad [ns]$$

$$t_{h(RD-CS)} = \frac{10^9}{f_{(BCLK)} \times 2} - 10 \quad [ns]$$

$$t_{h(WR-CS)} = \frac{10^9}{f_{(BCLK)} \times 2} - 10 \quad [ns]$$

$$t_{h(WR-DB)} = \frac{10^9}{f_{(BCLK)} \times 2} - 10 \quad [ns]$$

2. Values can be obtained from the following equations, according to BCLK frequency and external bus cycle.

$$t_{d(DB-WR)} = \frac{10^9 \times m}{f_{(BCLK)} \times 2} - 25 \quad [ns] \quad (\text{if external bus cycle is } a\phi + b\phi, m = (bx2)-1)$$

3. Values can be obtained from the following equations, according to BCLK frequency and external bus cycle.

$$t_{d(AD-ALE)} = \frac{10^9 \times n}{f_{(BCLK)} \times 2} - 20 \quad [ns] \quad (\text{if external bus cycle is } a\phi + b\phi, n = a)$$

4. Values can be obtained from the following equations, according to BCLK frequency and external bus cycle.

$$t_{h(ALE-AD)} = \frac{10^9 \times n}{f_{(BCLK)} \times 2} - 10 \quad [ns] \quad (\text{if external bus cycle is } a\phi + b\phi, n = a)$$

5. t_c ns is added when recovery cycle is inserted.

$$V_{CC1}=V_{CC2}=3.3V$$

Switching Characteristics

($V_{CC1} = V_{CC2} = 3.0$ to $3.6V$, $V_{SS} = 0V$ at $T_{opr} = -20$ to $85^{\circ}C$ unless otherwise specified)

Table 5.41 Memory Expansion Mode and Microprocessor Mode
(when accessing an external memory space with the multiplexed bus)

Symbol	Parameter	Measurement Condition	Standard		Unit
			Min.	Max.	
td(BCLK-AD)	Address Output Delay Time	See Figure 5.2		18	ns
th(BCLK-AD)	Address Output Hold Time (BCLK standard)		0		ns
th(RD-AD)	Address Output Hold Time (RD standard) ⁽⁵⁾		(Note 1)		ns
th(WR-AD)	Address Output Hold Time (WR standard) ⁽⁵⁾		(Note 1)		ns
td(BCLK-CS)	Chip-Select Signal Output Delay Time			18	ns
th(BCLK-CS)	Chip-Select Signal Output Hold Time (BCLK standard)		0		ns
th(RD-CS)	Chip-Select Signal Output Hold Time (RD standard) ⁽⁵⁾		(Note 1)		ns
th(WR-CS)	Chip-Select Signal Output Hold Time (WR standard) ⁽⁵⁾		(Note 1)		ns
td(BCLK-RD)	RD Signal Output Delay Time			18	ns
th(BCLK-RD)	RD Signal Output Hold Time		-3		ns
td(BCLK-WR)	WR Signal Output Delay Time			18	ns
th(BCLK-WR)	WR Signal Output Hold Time		0		ns
td(DB-WR)	Data Output delay Time (WR standard)		(Note 2)		ns
th(WR-DB)	Data Output Hold Time (WR standard) ⁽⁵⁾		(Note 1)		ns
td(BCLK-ALE)	ALE Signal Output Delay Time (BCLK standard)			18	ns
th(BCLK-ALE)	ALE Signal Output Hold Time (BCLK standard)		-2		ns
td(AD-ALE)	ALE Signal Output Delay Time (address standard)		(Note 3)		ns
th(ALE-AD)	ALE Signal Output Hold Time (address standard)		(Note 4)		ns
tdz(RD-AD)	Address Output Float Start Time			8	ns

NOTES:

1. Values can be obtained by the following equations, according to BCLK frequency.

$$th(RD - AD) = \frac{10^9}{f(BCLK) \times 2} - 10 \quad [ns]$$

$$th(WR - AD) = \frac{10^9}{f(BCLK) \times 2} - 10 \quad [ns]$$

$$th(RD - CS) = \frac{10^9}{f(BCLK) \times 2} - 10 \quad [ns]$$

$$th(WR - CS) = \frac{10^9}{f(BCLK) \times 2} - 10 \quad [ns]$$

$$th(WR - DB) = \frac{10^9}{f(BCLK) \times 2} - 20 \quad [ns]$$

2. Values can be obtained by the following equations, according to BCLK frequency and external bus cycles.

$$td(DB - WR) = \frac{10^9 \times m}{f(BCLK) \times 2} - 25 \quad [ns] \quad (\text{if external bus cycle is } a\phi + b\phi, m=(b+2)-1)$$

3. Values can be obtained by the following equations, according to BCLK frequency and external bus cycles.

$$td(AD - ALE) = \frac{10^9 \times n}{f(BCLK) \times 2} - 20 \quad [ns] \quad (\text{if external bus cycle is } a\phi + b\phi, n=a)$$

4. Values can be obtained by the following equations, according to BCLK frequency and external bus cycles.

$$th(ALE - AD) = \frac{10^9 \times n}{f(BCLK) \times 2} - 10 \quad [ns] \quad (\text{if external bus cycle is } a\phi + b\phi, n=a)$$

5. t_c ns is added when recovery cycle is inserted.

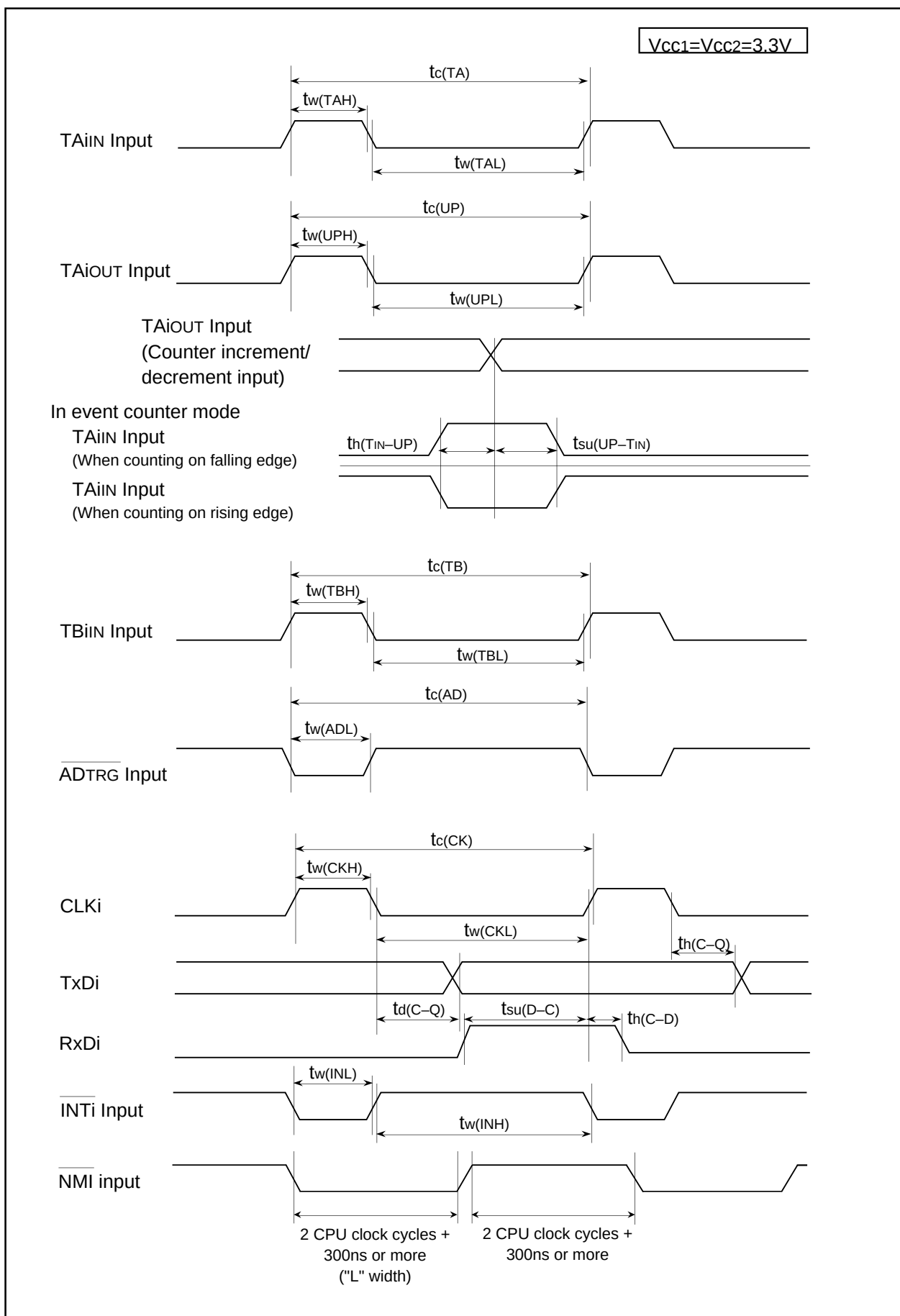
Figure 5.9 $V_{CC1}=V_{CC2}=3.3V$ Timing Diagram (3)

Table 5.43 Recommended Operating Conditions (Continued)**(V_{CC1}=V_{CC2}=4.2 to 5.5V, V_{SS}=0V at T_{opr} = -40 to 85°C (T version) unless otherwise specified)**

Symbol	Parameter		Standard			Unit
			Min.	Typ.	Max.	
f _(BCLK)	CPU Input Frequency	V _{CC1} =4.2 to 5.5V	0		32	MHz
f _(XIN)	Main Clock Input Frequency	V _{CC1} =4.2 to 5.5V	0		32	MHz
f _(XCIN)	Sub Clock Frequency			32.768	50	kHz
f _(Ring)	On-chip Oscillator Frequency (V _{CC1} =V _{CC2} =5.0V, T _{opr} =25° C)		0.5	1	2	MHz
f _(PLL)	PLL Clock Frequency	V _{CC1} =4.2 to 5.5V	10		32	MHz
t _{SU(PLL)}	Wait Time to Stabilize PLL Frequency Synthesizer	V _{CC1} =5.0V			5	ms

REVISION HISTORY	M32C/85 Group (M32C/85, M32C/85T) Datasheet
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Rev.	Date	Description	
		Page	Summary
0.30	Jul.18, 2003	–	New Document
0.40	Sep.30, 2003	2 to 3	Overview • Tables 1.1 and 1.2 M32C/85 Performance “Oscillator Stop Detect Function” added
		5	• Figure 1.2 ROM/RAM Capacity and Table 1.3. M32C/85 Group M30852ME-XXXGP and M30850ME-XXXGP/FP deleted
		6	• ROM capacity “192 Kbytes” deleted
0.40	Sep.30, 2003	7, 11, 12	• Figures 1.4 to 1.6 Pin Assignments Note 2 added
		10,14	- VREF pin changed from analog input pins to control pins.
		16 to 18	- SDA0 to SDA4 pins changed from output pins to I/O pins.
		17	- TA4OUT changed from input pin to I/O pin.
			- TA4IN pin changed from output pin to input pin.
		18	- ISRxD1 pin modified to ISRxD0 pin in port P8.
		19	- DA0 and DA1 pins changed from input pins to output pins.
0.40	Sep.30, 2003		- Symbol “P117” modified to “P114” and description from “8-bit” to “5-bit”.
			- Descriptions of ISTxD1 and BE1IN modified from “received data” to “transmit data”.
0.40	Sep.30, 2003		SFR
		44,45	- Notes written directly in the Tables.
0.50	Feb.05, 2004	2, 3	Overview • Tables 1.1 and 1.2 M32C/85 Performance “Shortest Instruction Execution Time” and “Power Consumption” values modified
		23	Memory • Figure 3.1 Memory Map Diagram modified
		24	SFR • “After RESET” values of PM 1, PM 2, D4INT, G0IRF, G1IRF, IDB0 to IDB1, TA0MR to TA4MR, TCSPR, DM0SL to DM3SL registers corrected
			• NOTES added to PM0 and TCSPR registers
0.50	Feb.05, 2004		Electrical Characteristics • Newly added
0.51	Feb.09, 2004		Electrical Characteristics
		52	• Table 5.6 Flash Memory Version Electrical Characteristics Note 4 changed
		59	• Figure 5.2 Vcc1=Vcc2=5V Timing Diagram (1) Notes 1 and 2 changed
		60	• Figure 5.3 Vcc1=Vcc2=5V Timing Diagram (2) Notes 1, 2, and 3 changed
		70	• Figure 5.6 Vcc1=Vcc2=3.3V Timing Diagram (1) Notes 1, 2, and 3 changed
		71	• Figure 5.7 Vcc1=Vcc2=3.3V Timing Diagram (2) Notes 1 and 2 changed
0.52	Mar.12, 2004		Overview
		2, 3	• Table 1.1 and 1.2 M32C/85 Group Performance Value of Power Consumption modified

REVISION HISTORY	M32C/85 Group (M32C/85, M32C/85T) Datasheet
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Rev.	Date	Description	
		Page	Summary
		50	Electrical Characteristics • Table 5.3 Electrical Characteristics Maximum values for Power Supply Current modified
		52	• Table 5.6 Flash Memory Version Electrical Characteristics Note 1. 100-cycle Products (D3, D5, U3, U5) deleted; Note 4 modified
		63	• Table 5.7 Flash Memory Version Program and Erase Voltage and Read Operation Voltage Characteristics (at Topr=0 to 60°C) deleted • Table 5.22 Electrical Characteristics Maximum values for Power Supply Consumption modified and standard values when “Topr=85°C while clock is stopped” deleted
1.00	Jun.01, 2004	-	M32C/85T (High-reliability version) added
		All Pages	Words standardized: On-chip oscillator, A/D converter and D/A converter
			Overview
		1	• 1.1 Applications Automobiles added
		2, 3	• Table 1.1 and Table 1.2 M32C/85 Group (M32C/85, M32C/85T) Performance M32C/85T added; note 3 added
		4	• Figure 1.1 M32C/85 Group (M32C/85, M32C/85T) Block Diagram Note 3 added
		5	• 1.4 Product Information Description modified
		5, 6	• Figure 1.2 ROM/RAM Capacity figure modified
		6	• Table 1.3 M32C/85 Group M32C/85T added
		6	• Figure 1.3 Product Numbering System M32C/85T added
		7	• Figure 1.4 Pin Assignment for 144-Pin Package Note 3 added
		12	• Figure 1.6 Pin Assignment for 100-Pin Package Note 5 added
		8 to 10	• Table 1.5 Pin Characteristics for 144-Pin Package Note 1 added
		13, 14	• Table 1.6 Pin Characteristics for 100-Pin Package Note 1 added
		15 to 18	• Table 1.7 Pin Description Notes added
			Memory
		22	• Figure 3.1 Memory Map Tables of internal ROM/internal RAM modified; note 2 modified; notes 4 and 5 added
			SFR
		23	• Note 2 added
		24	• PWCR0 and PWCR1 registers deleted
			• “Values after RESET” of the masked ROM version added to the FMR0 register
			• Note 1 added
			Electrical Characteristics
		46	• Table 5.2 Recommended Operating Conditions f(ripple), Vp-p(ripple), VCC, SVCC and note 1 deleted
		47	• Table 5.3 Electrical Characteristics RPULLUP value for the masked ROM version added

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